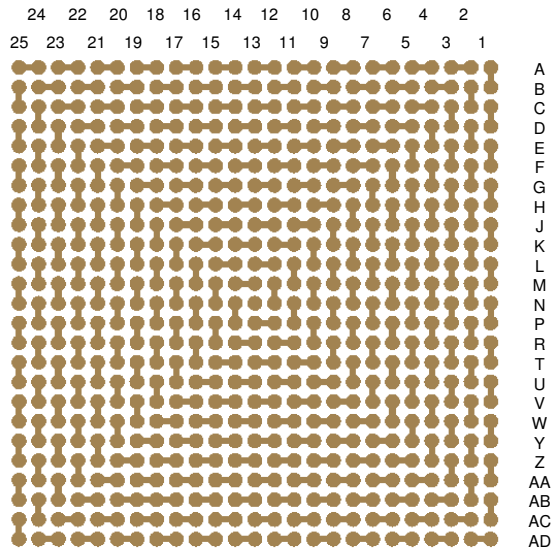


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.25mm [10 MIL].
 - 5) PAD Cu DIAMETER: 0.355mm [14 MIL].
 - 6) SUBSTRATE MATERIAL: BT.
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

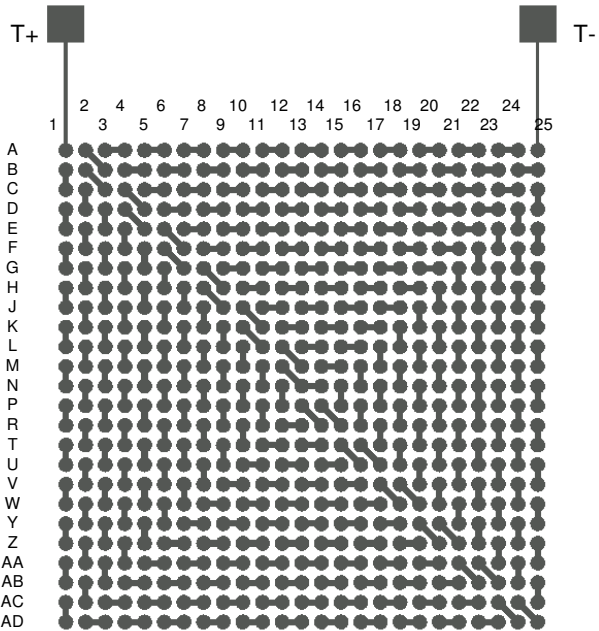
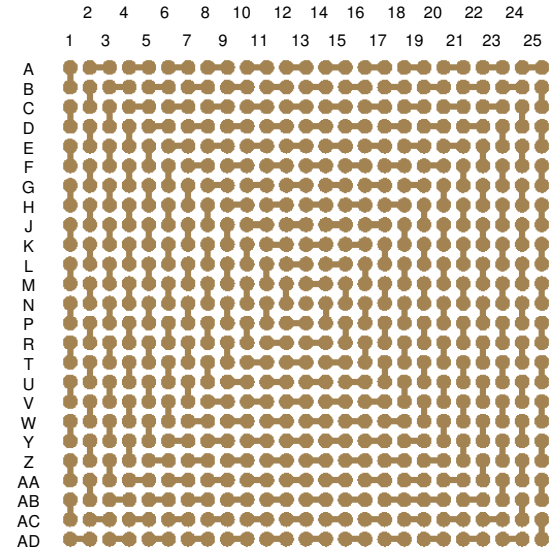
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA625T.5C-DC259Ö	Sn96.5/Ag3.0/Cu0.5	YES	YES	Ö
BGA625T.5-DC259D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED	APPROVALS	DATE				
X.XX +/- 0.01						
X.XXX +/- 0.005	DRAWN M.HART	1/16/20G1	TITLE BGA625T.5C-DC259Ö DAISY CHAIN DUMMY			
X.XXXX +/- 0.0005	ENG					
ANGLES +/- 0.5°	MFG		SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN	QA		6.5:1	A	552590	A
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS	CUST		DO NOT SCALE DRAWING		SHEET 1 OF 2	
THIRD ANGLE PROJECTION	REVISED					

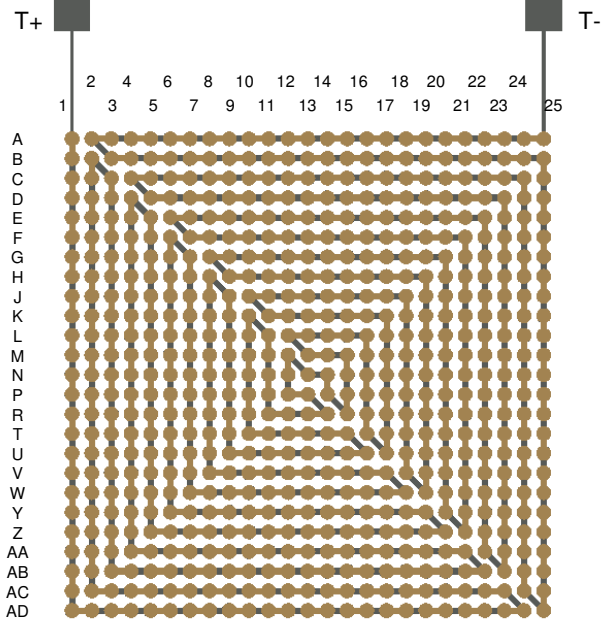
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm [14 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.25mm [10 MIL].

TopLine ®			
TITLE		BGA625T.5-DC259D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	552590	A
DO NOT SCALE DRAWING			SHEET 2 OF 2